PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data			
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V	
1.2 PCN No.		MDG/18/10703	
1.3 Title of PCN		TSMC (Taiwan) additional source for STM32F745/6 & STM32F756 products in M10/90nm technology	
1.4 Product Category		STM32F745/6 & STM32F756 products in M10/90nm technology	
1.5 Issue date		2018-04-25	

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	TSMC Fab14 (Taiwan)

4. Description of change		
	Old	New
4.1 Description	Front-end source: - ST Crolles CRL300 (France)	Front-end sources: - ST Crolles CRL300 (France) - Existing source - TSMC Fab14 (Taiwan) - Additional source - There is no change in the product functionality. Please refer to PCN 10703 – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change		
5.1 Motivation Due to the success on the market of STM32 devices, ST Microcontrollers Division decided qualify an additional front-end site to maintain state of the art service level to our customer thanks to extra capacity.		
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change	
	Change is visible through diffusion traceability plant, in the marking: - "VQ" for ST Crolles CRL300 (France) - "9R" for TSMC Fab14 (Taiwan) Please refer to PCN 10703 – Additional information attached document.

7. Timing / schedule	
7.1 Date of qualification results	2018-07-27
7.2 Intended start of delivery	2018-07-27
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation	
8.1 Description	10703 MDG-MCD RER1715 - PCN10333 - PCN10544 - PCN10595 - PCN10703 TSMC Taiwan.pdf

8.2 Qualification report and qualification results

Available (see attachment)

Issue Date

2018-04-25

9. Attachments (additional documentations)

10703 Public product.pdf 10703 PCN10703_Division Note M10 Additional Source.pdf 10703 MDG-MCD RER1715 - PCN10333 - PCN10544 - PCN10595 - PCN10703 TSMC Taiwan.pdf 10703 PCN10703_Additional information.pdf

10. Affected parts		
	10. 1 Current	10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F745IET6	
	STM32F745IGK6	
	STM32F745VET6	
	STM32F745VGT6	
	STM32F746IGK6	
	STM32F746IGT6	
	STM32F745IGT6	
	STM32F745ZET6	
	STM32F745ZGT6	
	STM32F746NEH6	
	STM32F746NGH6	
	STM32F746ZEY6TR	
	STM32F756IGK6	
	STM32F756IGT6	
	STM32F756NGH6	
	STM32F756VGT6	

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